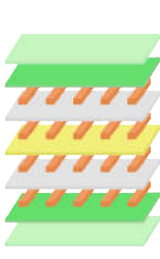
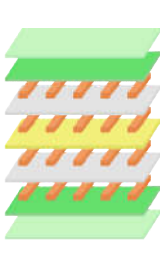


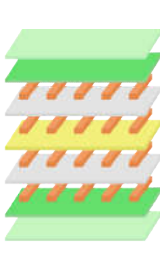


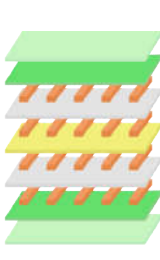
PCBGOGO Multi-layer PCB Standard Stackup

4-Layer PCB Board						
Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
0.4mm±0.1mm	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	3.8
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				
0.6mm±0.1mm	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm/0.08mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm/0.23mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm/0.08mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				
0.8mm±0.1mm	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				
1.0mm±0.1mm	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.53mm	4.5
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.2mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.73mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.6mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	1.13mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
2.0mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L2	Copper Foil	0.035mm	
			Core	FR-4	1.53mm	4.5
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
2.4mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L2	Copper Foil	0.035mm	
			Core	FR-4	1.93mm	4.5
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Note: The above is the standard stackup of PCBGOGO's 4-layer PCB board, and we may change the layer stackup according to latest material or technology. The custom stackup is available, feel free to contact us via service@pcbogo.com.

6-Layer PCB Board						
Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
0.8mm±0.1mm	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.0mm±0.1mm	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.5
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.5
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.2mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.2
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.6mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.53mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.53mm	4.2
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
2.0mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.73mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.73mm	4.2
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
2.4mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.93mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.93mm	4.2
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Bottom Soldermask	Soldermask Ink	0.025mm	3.5
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Note: The above is the standard stackup of PCBGOGO's 6-layer PCB board, and we may change the layer stackup according to latest material or technology. The custom stackup is available, feel free to contact us via service@pcbgogo.com.

8-Layer PCB Board						
Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.0mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	3.8
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	3.8
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	3.8
			L7	Copper Foil	0.035mm	
PP	PP	0.08mm	3.8			
L8	Copper Foil	0.035mm				
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

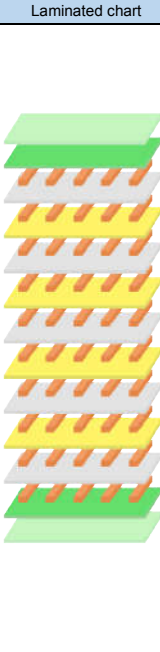
Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.2mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L7	Copper Foil	0.035mm	
PP	PP	0.11mm	4.2			
L8	Copper Foil	0.035mm				
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

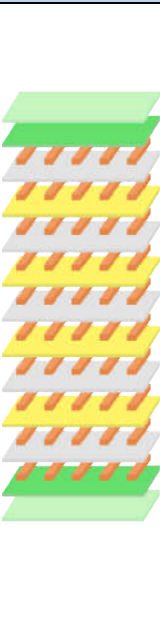
Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.6mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm/0.11mm	4.5
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm/0.23mm	4.5
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm/0.11mm	4.5
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.13mm/0.23mm	4.5
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm/0.11mm	4.5
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.13mm/0.23mm	4.5
			L7	Copper Foil	0.035mm	
PP	PP	0.18mm/0.11mm	4.5			
L8	Copper Foil	0.035mm				
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

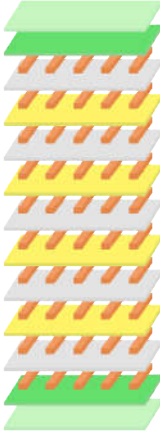
Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
2.0mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.5
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.5
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.5
			L7	Copper Foil	0.035mm	
			PP	PP	0.18mm	4.5
			L8	Copper Foil	0.035mm	
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

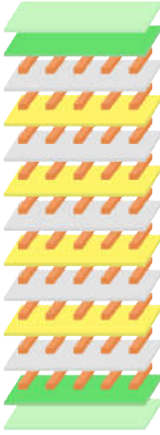
Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
2.4mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.53mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.53mm	4.2
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.53mm	4.2
			L7	Copper Foil	0.035mm	
			PP	PP	0.11mm	4.2
			L8	Copper Foil	0.035mm	
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Note: The above is the standard stackup of PCBGOGO's 8-layer PCB board, and we may change the layer stackup according to latest material or technology. The custom stackup is available, feel free to contact us via service@pcbgogo.com.

10-Layer PCB Board						
Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.2mm±0.1mm	10Z (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	3.8
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	3.8
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	3.8
			L7	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
			L8	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	3.8
			L9	Copper Foil	0.035mm	
			Pre-preg	PP	0.08mm	3.8
L10	Copper Foil	0.035mm				
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
1.6mm±10%	10Z (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L7	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L8	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.2
			L9	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
L10	Copper Foil	0.035mm				
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
2.0mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.5
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.5
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.5
			L7	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L8	Copper Foil	0.035mm	
			Core	FR-4	0.13mm	4.5
L9	Copper Foil	0.035mm				
Pre-preg	PP	0.18mm	4.5			
L10	Copper Foil	0.035mm				
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Board Thickness	Copper Thickness	Laminated chart	Name	Material	Material Thickness	Dielectric Constant
2.4mm±10%	1OZ (35um)		Top Silkscreen	Silkscreen Ink	0.01mm	
			Top Soldermask	Soldermask Ink	0.025mm	3.5
			L1	Copper Foil	0.035mm	
			Pre-preg	PP	0.18mm	4.5
			L2	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.5
			L3	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L4	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.5
			L5	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L6	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.5
			L7	Copper Foil	0.035mm	
			Pre-preg	PP	0.11mm	4.2
			L8	Copper Foil	0.035mm	
			Core	FR-4	0.33mm	4.5
L9	Copper Foil	0.035mm				
Pre-preg	PP	0.18mm	4.5			
L10	Copper Foil	0.035mm				
Bottom Soldermask	Soldermask Ink	0.025mm	3.5			
Bottom Silkscreen	Silkscreen Ink	0.01mm				

Note: The above is the standard stackup of PCBGOGO's 10-layer PCB board, and we may change the layer stackup according to latest material or technology. The custom stackup is available, feel free to contact us via service@pcbgo.com.